

Supporting Information

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Light-Intensity Switching of Graphene/WSe₂ Synaptic Devices

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Supplementary information for

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S1: Ids-Vds response at zero gate bias and under different illumination power.

The Dark0 is the initial dark current, and Dark(i), i=1,2,3,...,7 indicates the other dark current after illumination of respective laser power.

Figure S1: a) Ids-Vds and b) the enlarged curve after and during illumination of different power.

S2: Photovoltage under different illumination power and V_{bi} after illumination

In the photovoltaic effect, photogenerated e–h pairs are separated by an internal electric field that originates from the Schottky barrier at the interface between graphene and metal. The photovoltage (VPV) of the Gr/WSe2 vdWH can be calculated from the output curve under illumination, as shown in **[Figure S2](#page-3-0)**. The intercept of the Ids-Vds curve indicates the open-circuit voltage, that is the photovoltage. The slope of the I_{ds} -V_{ds} curve indicates the built-in electrical potential difference (Vbi). It is found that the Vbi is ~0.2 mV and the VPV is in the range of 0.4-0.6 mV. Due to asymmetry of the drain and source, there is a non-zero photovoltage $V_{PV} \approx \Delta V_D - \Delta V_S$, and a resultant photocurrent even at $V_{ds} = 0[1]$. The band diagram at the graphene-metal interface is shown in **[Figure S2](#page-3-0)**(c). Furthermore, to provide a theoretical outlook, the potential step Δ*V* is given by

$$
\Delta V = sgn (V_{gs} - V_{dirac}) \hbar v_f \sqrt{\pi \alpha |V_{gs} - V_{dirac}|} - \Delta E_{fm}
$$

$$
I_{ph} \propto (n_D^* \Delta V_D - n_S^* \Delta V_S)
$$

where $\alpha = 7.2 \times 10^{10} cm^{-2} V^{-1}$, $\hbar v_f = 5.52 eV \text{\AA}$, ΔE_{fm} is the fermi level shift of metal contacted graphene and n^* is the photogenerated carrier.

Figure S2: Photovoltage (V_{PV}) and built-in electrical potential difference (V_{bi}) induced by drain-source asymmetry under different optical power determined from the intercept and slope of the Ids-Vds curve. c) Band-bending resulting in photovoltage along the lateral junction.

Figure S3: Dynamic a) Ids and b) I_{ph} change at V_{gs}=0V and different P_{in} for a series of Vds.

Figure S4: The repeatability of the dynamic photocurrent current change at V_{gs}=0V and different P_{in} for a constant Vds=1 mV.

S3: *I***ds-***V***gs shift of the device after illumination.**

Figure S5. *I*ds-*V*gs shift after illumination. Dark line, red line, and blue line represent the dark current before illumination, the current under illumination at P_{in}= 0.5 mW, and the dark current after illumination, respectively.

S4: Modelling the effect of impurity density on the carrier transport in graphene.

The carrier transport in graphene in presence of scattering from charged impurities was modelled based on the work of Adman et al. [2]

$$
\frac{n^*}{n_{imp}} = 2r_s^2 C_0(r_s = 0.8, a = 4d\sqrt{\pi n^*})
$$

$$
\bar{n}=\frac{n_{imp}^2}{4n^*}
$$

where $C_0 = -1 + \frac{4E_1(a)}{(2+\pi r_S)^2} + \frac{2e^{-a}r_S}{1+2r_S} + (1+2r_S a)e^{2r_S a}(E_1[2r_S a] - E_1[a(1+2r_S a)]$

 $E_1(z) = \int_z^{\infty} t^{-1} e^{-t} dt$

and the exponential integral

The Dirac point shift depends on impurity density, which is given as:

$$
V_{dirac} = e \overline{n} C_{ox}
$$

where, C_{ox} is the capacitance per unit area of the dielectric layer (SiO₂). C_{ox}=ε/d, d being the thickness of the dielectric, which is equal to 300nm. Thus, the carrier density n is given by:

$$
n = \sqrt{n_g^2 + 4n_{min}^2}
$$

$$
n_{min} = \sqrt{\left(\frac{n^*/_2\right)^2 + 4n_{th}^2}
$$

where n_{th} is the thermal/intrinsic carrier concentration and ng is the carrier density change due to applied gate bias, Vg.

$$
n_{th} = \frac{\pi}{6} \left(\frac{k_B T}{\hbar v_f}\right)^2
$$

$$
n_g = \frac{c_{ox} (V_g - V_{dirac})}{e}
$$

The change in mobility due to change in impurity, density can be expressed as[3]:

$$
\frac{\mu}{\mu_{ref}} = \frac{n_{imp,ref}}{n_{imp}}
$$

Figure S6. Simulated transfer curve for the dark current Ids by increasing the impurity density for carrier scattering that affects the conductance of graphene channel.

Figure S7. Normalized photoresponse of the synaptic device at different P_{in} for a constant Vds=0.01 mV.

S5: Fabrication process

Figure S8. Fabrication process flow of Gr/WSe₂ vdWH devices. a) Dry-transferring mechanical exfoliated WSe₂ multi-layer flake to the SiO₂/Si substrate. b) WSe₂ with random shape is on the surface of SiO₂/Si substrate. c) Patterning the WSe₂ flake into a 15 um×5um rectangle through photolithograph and XF4 gas etching. d) Wet-transferring monolayer graphene over the WSe2. e) Patterning the monolayer graphene to a ribbon with length and width of 20 μm and 10 μm through photolithograph and O2 plasma dry-etching. f) Laser writing and e-beam evaporation are used to define contacts to the heterostructures, where source (s) and drain (d) Ti/Au (5 nm/50 nm) contacts are evaporated to contact the graphene ribbon. (g) Cross section of Gr/WSe₂ vdWH devices.

S6: Photoelectronic test system

Figure S9. Photoelectronic test system

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